

ABSTRACT OF THE DISCLOSURE

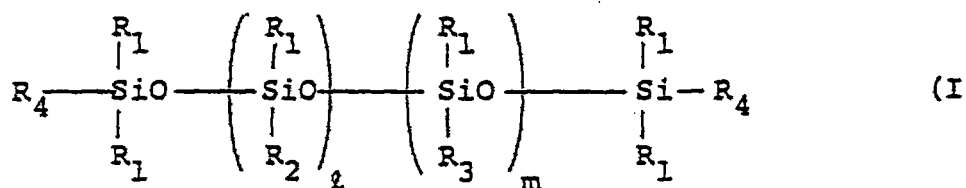
THERMOSETTING RESIN COMPOSITION

A thermosetting resin composition is prepared by mixing

(A) a phenol novolak resin having hydroxy groups and allyl-etherified hydroxy groups,

(B) a polymaleimide compound having two or more maleimide groups in the molecule, and

(C) at least one silicone resin having the following formula (I);



wherein R_1 and R_2 , which may be the same or different, are methyl or phenyl; R_3 and R_4 , which may be the same or different, are methyl, phenyl, hydrogen or a group having an amino group or an epoxy group but at least one of R_3 and R_4 is hydrogen or a group having an amino group or an epoxy group; and l and m , which may be the same or different, are a number of 0-400. The thermosetting resin composition of the present invention can be suitably used for encapsulating electric devices, for example, and gives, by curing, a cured resin product of high quality.